

**AMENDMENTS TO THE CLAIMS**

The following listing of claims is provided in accordance with 37 C.F.R. § 1.121.

1-32. (cancelled)

33. (previously presented) An electronic device, comprising:

a plurality of integrated circuit packages;

a contact surface electrically connected to each of said packages; and

a support arranged to engage each of said packages at a point spaced above said surface to prevent movement of said packages relative to said surface, wherein said support is secured to said surface.

34. (original) The device of claim 33, wherein each of said packages is contacted on its upper end.

35. (previously presented) The device of claim 33, wherein said support includes a pair of surfaces which engage each of said packages on two opposed surfaces, sandwiching said packages.

36. (original) The device of claim 35, wherein said support is resiliently biased against the sides of said packages.

37. (original) The device of claim 36, wherein said support contacts the side edges of said packages.

38. (original) The device of claim 33, wherein said support is made of a heat conducting material.

39. (original) The device of claim 38, wherein said material is a conformal material.

40. (original) The device of claim 38, wherein said material is a foam having heat conductive particles dispersed through it to increase its heat conductivity.

41. (original) The device of claim 37, wherein said support includes outwardly extending tabs arranged to engage depressions in said packages.

42. (original) The device of claim 33, wherein said support is directly connected to said surface.

43. (original) The device of claim 35, wherein said support is made at least in part of plastic foam.

44. (previously presented) The device of claim 43, wherein said support is made of plastic foam with a plurality of slots formed therein, each slot sized to resiliently engage one of said modules.

45. (original) The device of claim 44, wherein said foam includes adhesive on its bottom to secure said foam to said surface.

46-67. (cancelled)

68. (previously presented) An electronic device, comprising:  
a plurality of integrated circuit packages connected to a surface; and  
at least one rail coupled to the surface, wherein the rail extends along the sides of the plurality of integrated circuit packages and is configured to engage the plurality of integrated circuit packages.

69. (previously presented) The electronic device of claim 68, wherein the at least one rail is coupled to the surface by at least one post coupled to the surface and extending perpendicularly therefrom.

70. (previously presented) The electronic device of claim 69, wherein the at least one rail comprises tabs extending towards the plurality of integrated circuit packages.

71. (previously presented) An electronic device, comprising:  
a plurality of integrated circuit packages connected to a surface; and  
a cross piece coupled to the surface and extending over the plurality of integrated circuit packages in a direction transverse to the plurality of integrated circuit packages.

72. (previously presented) The electronic device of claim 71, wherein a plurality of supports extend from the cross piece towards the surface and are configured to engage the plurality of integrated circuit packages.

73. (previously presented) The electronic device of claim 71, wherein the cross piece is coupled to the surface by at least one post coupled to the surface and extending perpendicularly therefrom.

74. (previously presented) The electronic device of claim 71, wherein the cross piece consists essentially of a plastic and the plurality of supports consist essentially of a foam material.